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Live demonstration for 3.2T Co-Packaged Copper link – Part of the Co-Packaging demo: The OIF is the first organization to standardize an implementation for co-packaged copper solutions enabling broad support of “cabled-host” architectures. The common footprint supports a socket interface for the Optical Module and a compatible direct-to-substrate connection for Copper Modules. The 16 total modules are arranged in close proximity to the switch ASIC. This demonstration highlights the flexibility of the solution to support LR applications with multiple pluggable IO form factors.

QSFP-DD800 and OSFP800 Active Copper Cable (ACC) – Part of the PLL CEI LR demo: This 3-4m, 30AWG cable assembly pre-configured to work in an LR link and designed to stretch the physical reach >3m. Total power consumption <2W.

OSFP800 and QSFP-DD800 – Part of the PLL CEI VSR, MR, LR demos: Pluggable IO standard supporting up to 800Gb/s in aggregate over an 8 x 112Gb/s electrical interface.

Amphenol Corporation is one of the world’s largest designers and manufacturers of electrical, electronic and fiber optic connectors and interconnect systems, antennas, sensors and sensor-based products and coaxial and high-speed specialty cable.

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